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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	3537
Number of Logic Elements/Cells	75000
Total RAM Bits	8666112
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxma1d4f31c5n

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Symbol	Description	Condition	Minimum ⁽¹⁾	Typical	Maximum ⁽¹⁾	Unit
V_{CC}	Core voltage power supply	–C4, –I5, –C5, –C6	1.07	1.1	1.13	V
		–I3	1.12	1.15	1.18	V
V_{CCP}	Periphery circuitry, PCIe hard IP block, and transceiver PCS power supply	–C4, –I5, –C5, –C6	1.07	1.1	1.13	V
		–I3	1.12	1.15	1.18	V
V_{CCPGM}	Configuration pins power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
V_{CC_AUX}	Auxiliary supply	—	2.375	2.5	2.625	V
$V_{CCBAT}^{(2)}$	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.0	V
$V_{CCPD}^{(3)}$	I/O pre-driver power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V

⁽¹⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽²⁾ If you do not use the design security feature in Arria V devices, connect V_{CCBAT} to a 1.5-V, 2.5-V, or 3.0-V power supply. Arria V power-on reset (POR) circuitry monitors V_{CCBAT} . Arria V devices do not exit POR if V_{CCBAT} is not powered up.

⁽³⁾ V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25, or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V. V_{CCPD} must be 3.3 V when V_{CCIO} is 3.3 V.

Symbol	Description	Condition	Minimum ⁽¹⁾	Typical	Maximum ⁽¹⁾	Unit
V _{CCIO}	I/O buffers power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
		1.5 V	1.425	1.5	1.575	V
		1.35 V	1.283	1.35	1.418	V
		1.25 V	1.19	1.25	1.31	V
		1.2 V	1.14	1.2	1.26	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	—	1.425	1.5	1.575	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V _I	DC input voltage	—	−0.5	—	3.6	V
V _O	Output voltage	—	0	—	V _{CCIO}	V
T _J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	−40	—	100	°C
t _{RAMP} ⁽⁴⁾	Power supply ramp time	Standard POR	200 μs	—	100 ms	—
		Fast POR	200 μs	—	4 ms	—

⁽¹⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁴⁾ This is also applicable to HPS power supply. For HPS power supply, refer to t_{RAMP} specifications for standard POR when HPS_PORSEL = 0 and t_{RAMP} specifications for fast POR when HPS_PORSEL = 1.

Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications

Table 1-15: Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Arria V Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	—	—	—

- [Transceiver Specifications for Arria V GT and ST Devices](#) on page 1-29
Provides the specifications for transmitter, receiver, and reference clock I/O pin.

Switching Characteristics

This section provides performance characteristics of Arria V core and periphery blocks.

Transceiver Performance Specifications

Transceiver Specifications for Arria V GX and SX Devices

Table 1-20: Reference Clock Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O standards	1.2 V PCML, 1.4 V PCML,1.5 V PCML, 2.5 V PCML, Differential LVPECL ⁽²³⁾ , HCSL, and LVDS							
Input frequency from REFCLK input pins	—	27	—	710	27	—	710	MHz
Rise time	Measure at ±60 mV of differential signal ⁽²⁴⁾	—	—	400	—	—	400	ps
Fall time	Measure at ±60 mV of differential signal ⁽²⁴⁾	—	—	400	—	—	400	ps
Duty cycle	—	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	300 ⁽²⁵⁾ /2000	200	—	300 ⁽²⁵⁾ /2000	mV

⁽²³⁾ Differential LVPECL signal levels must comply to the minimum and maximum peak-to-peak differential input voltage specified in this table.

⁽²⁴⁾ REFCLK performance requires to meet transmitter REFCLK phase noise specification.

⁽²⁵⁾ The maximum peak-to peak differential input voltage of 300 mV is allowed for DC coupled link.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$f_{\text{OUT_EXT}}$	Output frequency for external clock output	–3 speed grade	—	—	670 ⁽⁶³⁾	MHz
		–4 speed grade	—	—	670 ⁽⁶³⁾	MHz
		–5 speed grade	—	—	622 ⁽⁶³⁾	MHz
		–6 speed grade	—	—	500 ⁽⁶³⁾	MHz
t_{OUTDUTY}	Duty cycle for external clock output (when set to 50%)	—	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	—	10	ns
$t_{\text{DYCONFIGCLK}}$	Dynamic configuration clock for <code>mgmt_clk</code> and <code>scanclk</code>	—	—	—	100	MHz
t_{LOCK}	Time required to lock from end-of-device configuration or deassertion of <code>areset</code>	—	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	—	1	ms
f_{CLBW}	PLL closed-loop bandwidth	Low	—	0.3	—	MHz
		Medium	—	1.5	—	MHz
		High ⁽⁶⁴⁾	—	4	—	MHz
$t_{\text{PLL_PSERR}}$	Accuracy of PLL phase shift	—	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the <code>areset</code> signal	—	10	—	—	ns
t_{INCCJ} ⁽⁶⁵⁾⁽⁶⁶⁾	Input clock cycle-to-cycle jitter	$F_{\text{REF}} \geq 100 \text{ MHz}$	—	—	0.15	UI (p-p)
		$F_{\text{REF}} < 100 \text{ MHz}$	—	—	±750	ps (p-p)

⁽⁶⁴⁾ High bandwidth PLL settings are not supported in external feedback mode.⁽⁶⁵⁾ A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source with jitter < 120 ps.⁽⁶⁶⁾ F_{REF} is f_{IN}/N , specification applies when $N = 1$.

Memory Output Clock Jitter Specifications

Table 1-45: Memory Output Clock Jitter Specifications for Arria V Devices

The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard.

The memory output clock jitter is applicable when an input jitter of 30 ps (p-p) is applied with bit error rate (BER) 10^{-12} , equivalent to 14 sigma.

Altera recommends using the UniPHY intellectual property (IP) with PHYCLK connections for better jitter performance.

Parameter	Clock Network	Symbol	-I3, -C4		-I5, -C5		-C6		Unit
			Min	Max	Min	Max	Min	Max	
Clock period jitter	PHYCLK	$t_{JIT(per)}$	-41	41	-50	50	-55	55	ps
Cycle-to-cycle period jitter	PHYCLK	$t_{JIT(cc)}$	63		90		94		ps

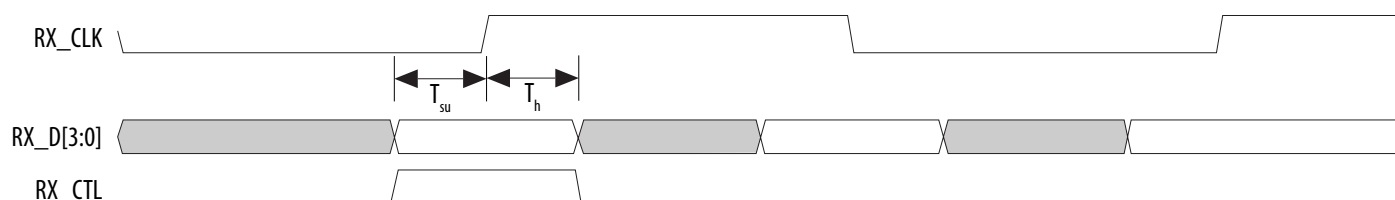
OCT Calibration Block Specifications

Table 1-46: OCT Calibration Block Specifications for Arria V Devices

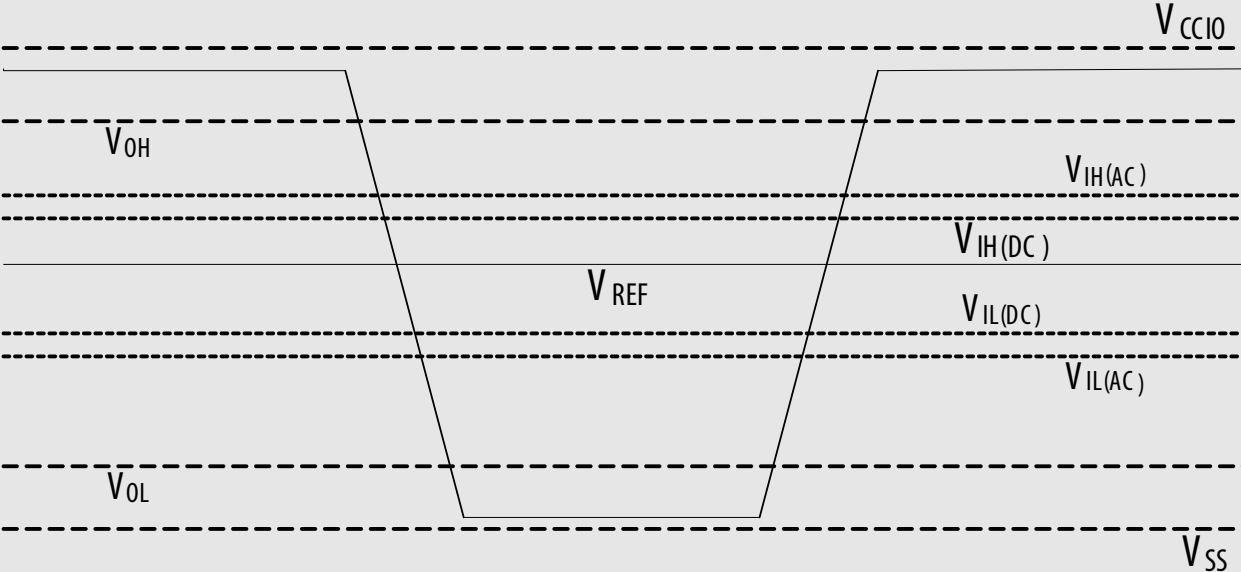
Symbol	Description	Min	Typ	Max	Unit
OCTUSRCLK	Clock required by OCT calibration blocks	—	—	20	MHz
T_{OCTCAL}	Number of OCTUSRCLK clock cycles required for R_S OCT/ R_T OCT calibration	—	1000	—	Cycles
$T_{OCTSHIFT}$	Number of OCTUSRCLK clock cycles required for OCT code to shift out	—	32	—	Cycles
T_{RS_RT}	Time required between the <code>dyn_term_ctrl</code> and <code>oe</code> signal transitions in a bidirectional I/O buffer to dynamically switch between R_S OCT and R_T OCT	—	2.5	—	ns

Table 1-57: RGMII RX Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Unit
T_{clk} (1000Base-T)	RX_CLK clock period	—	8	ns
T_{clk} (100Base-T)	RX_CLK clock period	—	40	ns
T_{clk} (10Base-T)	RX_CLK clock period	—	400	ns
T_{su}	RX_D/RX_CTL setup time	1	—	ns
T_h	RX_D/RX_CTL hold time	1	—	ns

Figure 1-14: RGMII RX Timing Diagram**Table 1-58: Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices**

Symbol	Description	Min	Typ	Max	Unit
T_{clk}	MDC clock period	—	400	—	ns
T_d	MDC to MDIO output data delay	10	—	20	ns
T_s	Setup time for MDIO data	10	—	—	ns
T_h	Hold time for MDIO data	0	—	—	ns

Term	Definition
Single-ended voltage referenced I/O standard	<p>The JEDEC standard for the SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.</p> <p>The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing.</p> <p>Single-Ended Voltage Referenced I/O Standard</p> 
t_C	High-speed receiver/transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including the t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on high-speed transmitter output clock.

Term	Definition
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—Clock boost factor

Document Revision History

Date	Version	Changes
December 2016	2016.12.09	<ul style="list-style-type: none"> Updated V_{ICM} (AC coupled) specifications in Receiver Specifications for Arria V GX and SX Devices table. Added maximum specification for T_d in Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices table. Updated T_{init} specifications in the following tables: <ul style="list-style-type: none"> FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Arria V Devices FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices AS Timing Parameters for AS $\times 1$ and $\times 4$ Configurations in Arria V Devices PS Timing Parameters for Arria V Devices
June 2016	2016.06.10	<ul style="list-style-type: none"> Changed pin capacitance to maximum values. Updated SPI Master Timing Requirements for Arria V Devices table. <ul style="list-style-type: none"> Added T_{su} and T_h specifications. Removed T_{dinmax} specifications. Updated SPI Master Timing Diagram. Updated T_{clk} spec from maximum to minimum in I²C Timing Requirements for Arria V Devices table.

Date	Version	Changes
July 2014	3.8	<ul style="list-style-type: none"> Added a note in Table 3, Table 4, and Table 5: The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements. Updated V_{CC_HPS} specification in Table 5. Added a note in Table 19: Differential inputs are powered by V_{CCPD} which requires 2.5 V. Updated "Minimum differential eye opening at the receiver serial input pins" specification in Table 20 and Table 21. Updated description in "HPS PLL Specifications" section. Updated VCO range maximum specification in Table 39. Updated T_d and T_h specifications in Table 45. Added T_h specification in Table 47 and Figure 13. Updated a note in Figure 20, Figure 21, and Figure 23 as follows: Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required. Removed "Remote update only in AS mode" specification in Table 58. Added DCLK device initialization clock source specification in Table 60. Added description in "Configuration Files" section: The IOCSR .rbf size is specifically for the Configuration via Protocol (CvP) feature. Removed $f_{MAX_RU_CLK}$ specification in Table 63.
February 2014	3.7	<ul style="list-style-type: none"> Updated $V_{CCRSTCLK_HPS}$ maximum specification in Table 1. Added $V_{CC_AUX_SHARED}$ specification in Table 1.
December 2013	3.6	<ul style="list-style-type: none"> Added "HPS PLL Specifications". Added Table 24, Table 39, and Table 40. Updated Table 1, Table 3, Table 5, Table 19, Table 20, Table 21, Table 38, Table 41, Table 42, Table 43, Table 44, Table 45, Table 46, Table 47, Table 48, Table 49, Table 50, Table 51, Table 55, Table 56, and Table 59. Updated Figure 7, Figure 13, Figure 15, Figure 16, and Figure 19. Removed table: GPIO Pulse Width for Arria V Devices.

2017.02.10

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This document covers the electrical and switching characteristics for Arria V GZ devices. Electrical characteristics include operating conditions and power consumption. Switching characteristics include transceiver specifications, core, and periphery performance. This document also describes I/O timing, including programmable I/O element (IOE) delay and programmable output buffer delay.

Related Information**[Arria V Device Overview](#)**

For information regarding the densities and packages of devices in the Arria V GZ family.

Electrical Characteristics

Operating Conditions

When you use Arria V GZ devices, they are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of Arria V GZ devices, you must consider the operating requirements described in this datasheet.

Arria V GZ devices are offered in commercial and industrial temperature grades.

Commercial devices are offered in –3 (fastest) and –4 core speed grades. Industrial devices are offered in –3L and –4 core speed grades. Arria V GZ devices are offered in –2 and –3 transceiver speed grades.

Table 2-1: Commercial and Industrial Speed Grade Offering for Arria V GZ Devices

C = Commercial temperature grade; I = Industrial temperature grade.

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Symbol	Description	Condition	Minimum ⁽¹¹⁴⁾	Typical	Maximum ⁽¹¹⁴⁾	Unit
V _I	DC input voltage	—	−0.5	—	3.6	V
V _O	Output voltage	—	0	—	V _{CCIO}	V
T _J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	−40	—	100	°C
t _{RAMP}	Power supply ramp time	Standard POR	200 μs	—	100 ms	—
		Fast POR	200 μs	—	4 ms	—

Recommended Transceiver Power Supply Operating Conditions

Table 2-6: Recommended Transceiver Power Supply Operating Conditions for Arria V GZ Devices

Symbol	Description	Minimum ⁽¹¹⁸⁾	Typical	Maximum ⁽¹¹⁸⁾	Unit
V _{CCA_GXBL} (119), (120)	Transceiver channel PLL power supply (left side)	2.85	3.0	3.15	V
		2.375	2.5	2.625	
V _{CCA_GXBR} (119), (120)	Transceiver channel PLL power supply (right side)	2.85	3.0	3.15	V
		2.375	2.5	2.625	
V _{CCHIP_L}	Transceiver hard IP power supply (left side)	0.82	0.85	0.88	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side)	0.82	0.85	0.88	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side)	0.82	0.85	0.88	V

⁽¹¹⁴⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽¹¹⁸⁾ This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽¹¹⁹⁾ This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

⁽¹²⁰⁾ When using ATX PLLs, the supply must be 3.0 V.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration ⁽¹⁴⁶⁾	$V_{CCR_GXB} = 1.0\text{ V}$ ($V_{ICM} = 0.75\text{ V}$)	—	—	1.8	—	—	1.8	V
	$V_{CCR_GXB} = 0.85\text{ V}$ ($V_{ICM} = 0.6\text{ V}$)	—	—	2.4	—	—	2.4	V
Minimum differential eye opening at receiver serial input pins ⁽¹⁴⁷⁾⁽¹⁴⁸⁾	—	85	—	—	85	—	—	mV
Differential on-chip termination resistors	85- Ω setting	—	$85 \pm 30\%$	—	—	$85 \pm 30\%$	—	Ω
	100- Ω setting	—	$100 \pm 30\%$	—	—	$100 \pm 30\%$	—	Ω
	120- Ω setting	—	$120 \pm 30\%$	—	—	$120 \pm 30\%$	—	Ω
	150- Ω setting	—	$150 \pm 30\%$	—	—	$150 \pm 30\%$	—	Ω

⁽¹⁴⁶⁾ The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to $4 \times (\text{absolute } V_{MAX} \text{ for receiver pin} - V_{ICM})$.

⁽¹⁴⁷⁾ The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

⁽¹⁴⁸⁾ Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Core Performance Specifications

Clock Tree Specifications

Table 2-33: Clock Tree Performance for Arria V GZ Devices

Symbol	Performance		Unit
	C3, I3L	C4, I4	
Global and Regional Clock	650	580	MHz
Periphery Clock	500	500	MHz

PLL Specifications

Table 2-34: PLL Specifications for Arria V GZ Devices

Symbol	Parameter	Min	Typ	Max	Unit
$f_{IN}^{(167)}$	Input clock frequency (C3, I3L speed grade)	5	—	800	MHz
	Input clock frequency (C4, I4 speed grade)	5	—	650	MHz
f_{INPFD}	Input frequency to the PFD	5	—	325	MHz
f_{FINPFD}	Fractional Input clock frequency to the PFD	50	—	160	MHz
$f_{VCO}^{(168)}$	PLL VCO operating range (C3, I3L speed grade)	600	—	1600	MHz
	PLL VCO operating range (C4, I4 speed grade)	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	40	—	60	%

⁽¹⁶⁷⁾ This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

⁽¹⁶⁸⁾ The VCO frequency reported by the Quartus II software in the **PLL Usage Summary** section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

Symbol	Parameter	Min	Typ	Max	Unit
$f_{OUT}^{(169)}$	Output frequency for an internal global or regional clock (C3, I3L speed grade)	—	—	650	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grade)	—	—	580	MHz
$f_{OUT_EXT}^{(169)}$	Output frequency for an external clock output (C3, I3L speed grade)	—	—	667	MHz
	Output frequency for an external clock output (C4, I4 speed grade)	—	—	533	MHz
$t_{OUTDUTY}$	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	10	ns
$f_{DYCONFIGCLK}$	Dynamic configuration clock for <code>mgmt_clk</code> and <code>scanclk</code>	—	—	100	MHz
t_{LOCK}	Time required to lock from the end-of-device configuration or deassertion of <code>areset</code>	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/ delays)	—	—	1	ms
f_{CLBW}	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth ⁽¹⁷⁰⁾	—	4	—	MHz
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the <code>areset</code> signal	10	—	—	ns

⁽¹⁶⁹⁾ This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.

⁽¹⁷⁰⁾ High bandwidth PLL settings are not supported in external feedback mode.

DLL Range Specifications

Table 2-47: DLL Range Specifications for Arria V GZ Devices

Arria V GZ devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Parameter	C3, I3L	C4, I4	Unit
DLL operating frequency range	300 – 890	300 – 890	MHz

DQS Logic Block Specifications

Table 2-48: DQS Phase Offset Delay Per Setting for Arria V GZ Devices

The typical value equals the average of the minimum and maximum values.

The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a –3 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is $[625 \text{ ps} + (10 \times 11 \text{ ps}) \pm 20 \text{ ps}] = 735 \text{ ps} \pm 20 \text{ ps}$.

Speed Grade	Min	Max	Unit
C3, I3L	8	15	ps
C4, I4	8	16	ps

Table 2-49: DQS Phase Shift Error Specification for DLL-Delayed Clock ($t_{\text{DQS_PSERR}}$) for Arria V GZ Devices

This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a –3 speed grade is $\pm 84 \text{ ps}$ or $\pm 42 \text{ ps}$.

Number of DQS Delay Buffers	C3, I3L	C4, I4	Unit
1	30	32	ps
2	60	64	ps
3	90	96	ps

Duty Cycle Distortion (DCD) Specifications

Table 2-52: Worst-Case DCD on Arria V GZ I/O Pins

The DCD numbers do not cover the core clock network.

Symbol	C3, I3L		C4, I4		Unit
	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	%

Configuration Specification

POR Specifications

Table 2-53: Fast and Standard POR Delay Specification for Arria V GZ Devices

Select the POR delay based on the MSEL setting as described in the “Configuration Schemes for Arria V Devices” table in the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

POR Delay	Minimum (ms)	Maximum (ms)
Fast	4	12 ⁽²⁰²⁾
Standard	100	300

Related Information

[Configuration, Design Security, and Remote System Upgrades in Arria V Devices](#)

⁽²⁰²⁾ The maximum pulse width of the fast POR delay is 12 ms, providing enough time for the PCIe hard IP to initialize after the POR trip.

Note: When you enable the decompression or design security feature, the DCLK-to-DATA[] ratio varies for FPP ×8, FPP ×16, and FPP ×32. For the respective DCLK-to-DATA[] ratio, refer to the "DCLK-to-DATA[] Ratio for Arria V GZ Devices" table.

Table 2-56: FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1

Use these timing parameters when the decompression and design security features are disabled.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μs
t_{STATUS}	nSTATUS low pulse width	268	1,506 ⁽²⁰⁵⁾	μs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁰⁶⁾	μs
t_{CF2CK} (207)	nCONFIG high to first rising edge on DCLK	1,506	—	μs
t_{ST2CK} ⁽²⁰⁷⁾	nSTATUS high to first rising edge of DCLK	2	—	μs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP ×8/×16)	—	125	MHz
	DCLK frequency (FPP ×32)	—	100	MHz
t_{CD2UM}	CONF_DONE high to user mode ⁽²⁰⁸⁾	175	437	μs

⁽²⁰⁵⁾ This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

⁽²⁰⁶⁾ This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

⁽²⁰⁷⁾ If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Date	Version	Changes
July 2014	3.8	<ul style="list-style-type: none"> Updated Table 21. Updated Table 22 V_{OCM} (DC Coupled) condition. Updated the DCLK note to Figure 6, Figure 7, and Figure 9. Added note to Table 5 and Table 6. Added the DCLK specification to Table 50. Added note to Table 51. Updated the list of parameters in Table 53.
February 2014	3.7	Updated Table 28.
December 2013	3.6	<ul style="list-style-type: none"> Updated Table 2, Table 13, Table 18, Table 19, Table 22, Table 30, Table 33, Table 37, Table 38, Table 45, Table 46, Table 47, Table 56, Table 49. Updated “PLL Specifications”.
August 2013	3.5	Updated Table 28.
August 2013	3.4	<ul style="list-style-type: none"> Removed Preliminary tags for Table 2, Table 4, Table 5, Table 14, Table 27, Table 28, Table 29, Table 31, Table 32, Table 43, Table 45, Table 46, Table 47, Table 48, Table 49, Table 50, and Table 54. Updated Table 2 and Table 28.
June 2013	3.3	Updated Table 23, Table 28, Table 51, and Table 55.
May 2013	3.2	<ul style="list-style-type: none"> Added Table 23. Updated Table 5, Table 22, Table 26, and Table 57. Updated Figure 6, Figure 7, Figure 8, and Figure 9.
March 2013	3.1	<ul style="list-style-type: none"> Updated Table 2, Table 6, Table 7, Table 8, Table 19, Table 22, Table 26, Table 29, Table 52. Updated “Maximum Allowed Overshoot and Undershoot Voltage”.
December 2012	3.0	Initial release.